



# LEVEL 2\* LABORATORY TRAINING ON SEMICONDUCTOR PACKAGING

\* FOR PARTICIPANTS WITH 1 OR 2 YEARS  
OF DOMAIN EXPERTISE



27TH FEB TO  
3RD MARCH  
2023

## HIGHLIGHTS OF THE EVENT

HANDS-ON TRAINING | ADVANCED PACKAGING PROCESSES |  
INTERACT WITH RENOWNED EXPERTS | NETWORKING WITH  
PROSPECTIVE COLLABORATORS

CO-ORGANIZED BY



VENUE

CMTI & STARC  
BANGALORE

THE WORKSHOP SHALL INCLUDE EXPERT TALKS AND LECTURES BY LEADING PROFESSIONALS FROM INDUSTRIES AND ACADEMIA. THESE TALKS SHALL COVER THE LATEST TRENDS, RECENT ADVANCEMENTS, PAIN POINTS IN PACKAGING TECHNOLOGIES INCLUDING FUTURE PERSPECTIVES.

# LECTURES

# HANDS-ON

@  
SENSOR TECHNOLOGY  
DEVELOPMENT CENTRE (STDC), CMTI  
&  
STARC, DRDO

WAFER DICING  
WIRE BONDING  
FLIP CHIP BONDING  
BOND TESTING  
E-BEAM WELDING  
WAFER BONDING  
ELECTROPLATING / THIN FILM  
DEPOSITION  
LEAK TESTING / ELECTRICAL  
CHARACTERIZATION

## COURSE FEE

1. INDUSTRY - RS. 30,000
2. FACULTY - RS. 15,000
3. STUDENTS - RS. 10,000

## FOR ISSS MEMBERS

1. INDUSTRY - RS. 25,000
2. FACULTY - RS. 10,000
3. STUDENTS - RS. 8,000

# REGISTER



write to : [csvtc@cmti.res.in](mailto:csvtc@cmti.res.in)